# **IGBT** with Monolithic Free **Wheeling Diode**

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, and provides superior performance in demanding switching applications, offering both low on-state voltage and minimal switching loss. The IGBT is well suited for resonant or soft switching applications.

#### **Features**

- Extremely Efficient Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Losses in IH Cooker Application
- Reliable and Cost Effective Single Die Solution
- This is a Pb-Free Device

### **Typical Applications**

- Inductive Heating
- Consumer Appliances
- Soft Switching

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	I <sub>C</sub>	80 40	Α
Pulsed collector current, $T_{pulse}$ limited by $T_{Jmax}$ , 10 $\mu s$ pulse, $V_{GE}$ = 15 $V$	I <sub>CM</sub>	120	А
Diode forward current @ Tc = 25°C @ Tc = 100°C	l <sub>F</sub>	80 40	А
Diode pulsed current, $T_{pulse}$ limited by $T_{Jmax}$ , 10 $\mu s$ pulse, $V_{GE}$ = 0 $V$	I <sub>FM</sub>	120	А
Gate-emitter voltage Transient Gate-emitter voltage $(T_{pulse} = 5 \mu s, D < 0.10)$	$V_{GE}$	±20 ±25	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	384 192	W
Operating junction temperature range	TJ	-40 to +175	°C
Storage temperature range	T <sub>stg</sub>	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

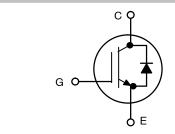
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

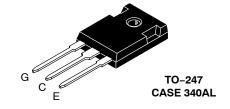


## ON Semiconductor®

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40 A, 1200 V **V<sub>CEsat</sub>** = 2.30 **V**  $E_{off} = 0.95 \text{ mJ}$ 





### **MARKING DIAGRAM**



= Assembly Location

= Year WW = Work Week = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping
NGTB40N120IHRWG	TO-247 (Pb-Free)	30 Units / Rail

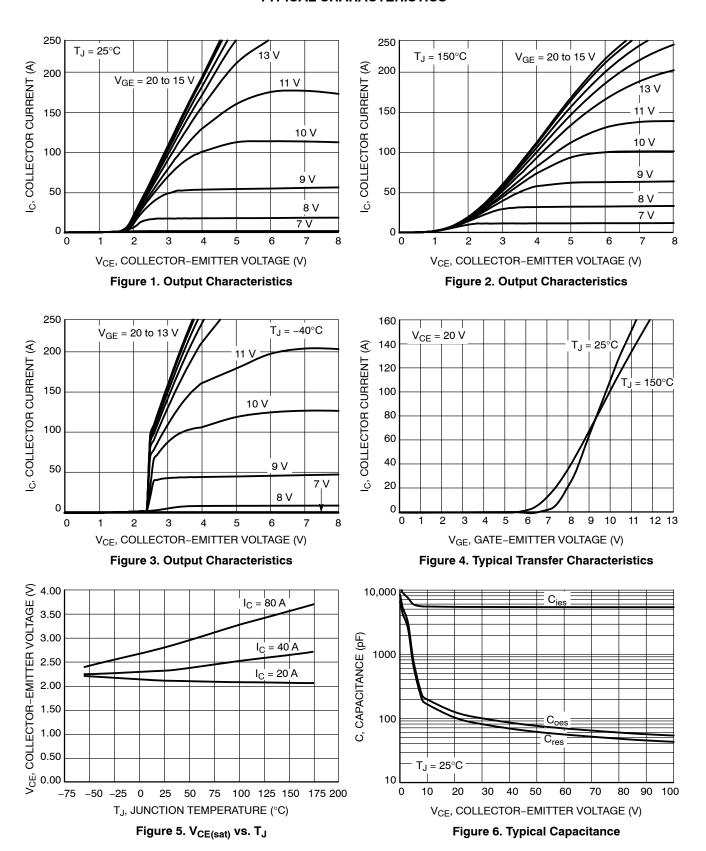
### THERMAL CHARACTERISTICS

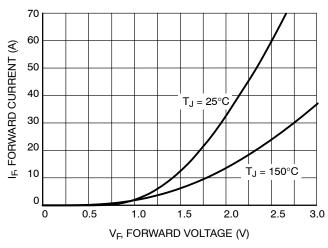
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case	$R_{ heta JC}$	0.39	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE}$ = 0 V, $I_C$ = 500 $\mu A$	V <sub>(BR)CES</sub>	1200	_	-	V
Collector-emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>CEsat</sub>	- -	2.30 2.70	2.55	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	V <sub>GE(th)</sub>	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J =</sub> 175°C	I <sub>CES</sub>	- -	- -	0.2 2.8	mA
Gate leakage current, collector-emitter short-circuited	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	100	nA
DYNAMIC CHARACTERISTIC						
Input capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>ies</sub>	-	5320	-	pF
Output capacitance		C <sub>oes</sub>	-	124	-	
Reverse transfer capacitance		C <sub>res</sub>	-	100	-	
Gate charge total		$Q_g$	-	225	-	nC
Gate to emitter charge	V <sub>CE</sub> = 600 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	$Q_{ge}$	-	36	-	
Gate to collector charge		$Q_{gc}$	-	98	-	
SWITCHING CHARACTERISTIC, INDUCT	IVE LOAD					
Turn-off delay time	$T_{J} = 25^{\circ}C$ $V_{CC} = 600 \text{ V, } I_{C} = 40 \text{ A}$ $R_{g} = 10 \Omega$ $V_{GE} = 0 \text{ V/ } 15 \text{ V}$	t <sub>d(off)</sub>	-	230	-	ns
Fall time		t <sub>f</sub>	-	120	-	
Turn-off switching loss		E <sub>off</sub>	-	0.95	-	mJ
Turn-off delay time	$T_{J} = 150^{\circ}\text{C}$ $V_{CC} = 600 \text{ V, } I_{C} = 40 \text{ A}$ $R_{g} = 10 \Omega$	t <sub>d(off)</sub>	-	245	-	ns
Fall time		t <sub>f</sub>	-	180	-	
Turn-off switching loss	V <sub>GE</sub> = 0 V/ 15V	E <sub>off</sub>	-	2.10	-	mJ
DIODE CHARACTERISTIC						
Forward voltage	$V_{GE} = 0 \text{ V}, I_F = 40 \text{ A}$ $V_{GE} = 0 \text{ V}, I_F = 40 \text{ A}, T_J = 175^{\circ}\text{C}$	V <sub>F</sub>	- -	2.10 3.30	2.60	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

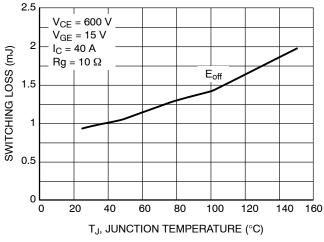




16 V<sub>GE</sub>, GATE-EMITTER VOLTAGE (V) 14 12 10 6 V<sub>CE</sub> = 600 V 2 V<sub>GE</sub> = 15 V  $I_{C} = 40 \text{ A}$ 0 0 50 100 150 200 250 Q<sub>G</sub>, GATE CHARGE (nC)

Figure 7. Diode Forward Characteristics

Figure 8. Typical Gate Charge



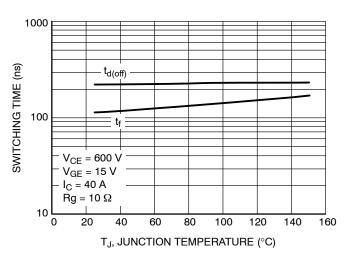
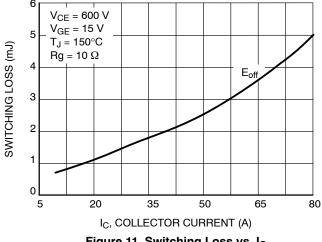


Figure 9. Switching Loss vs. Temperature

Figure 10. Switching Time vs. Temperature



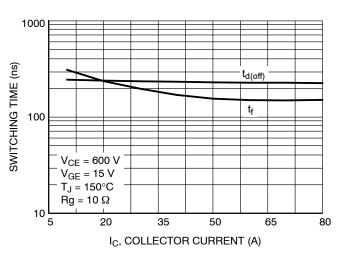
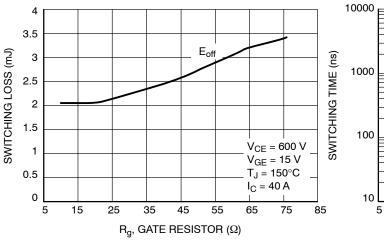


Figure 11. Switching Loss vs. I<sub>C</sub>

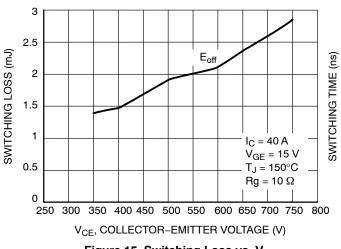
Figure 12. Switching Time vs. I<sub>C</sub>



10000 1000 V<sub>CE</sub> = 600 V V<sub>GE</sub> = 15 V T<sub>J</sub> = 150°C I<sub>C</sub> = 40 A 10 5 15 25 35 45 55 65 75 85 R<sub>g</sub>, GATE RESISTOR (Ω)

Figure 13. Switching Loss vs. Ra

Figure 14. Switching Time vs.  $R_g$ 



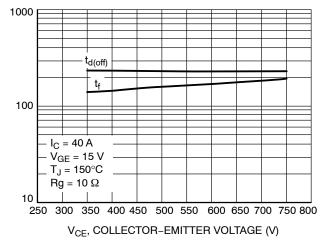
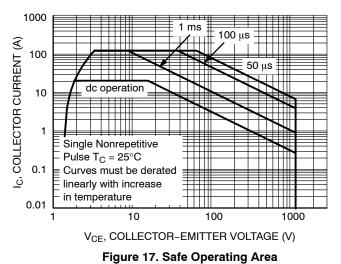


Figure 15. Switching Loss vs. V<sub>CE</sub>

Figure 16. Switching Time vs. V<sub>CE</sub>



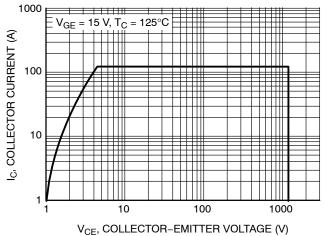


Figure 18. Reverse Bias Safe Operating Area

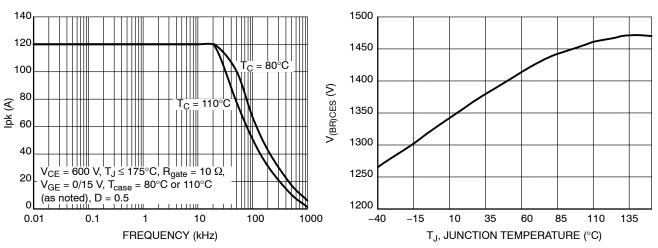


Figure 19. Collector Current vs. Switching Frequency

Figure 20. Typical  $V_{(BR)CES}$  vs. Temperature

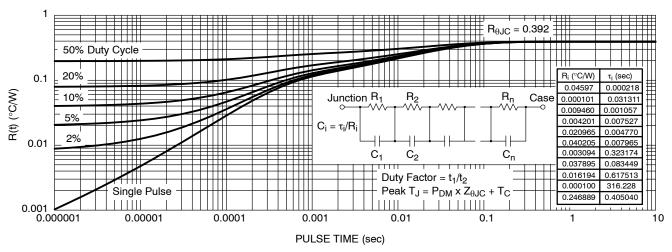


Figure 21. IGBT Transient Thermal Impedance

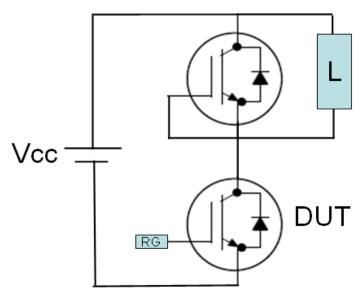


Figure 22. Test Circuit for Switching Characteristics

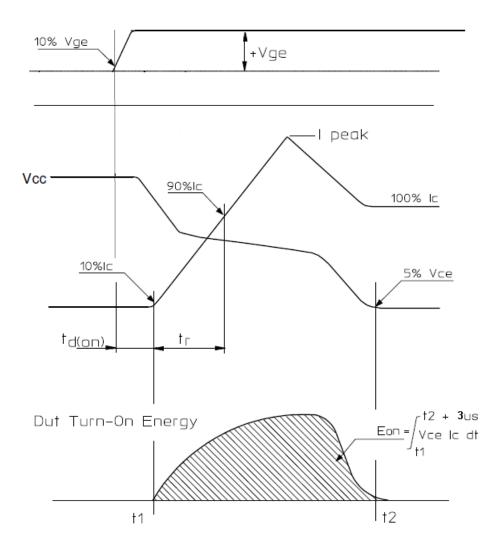


Figure 23. Definition of Turn On Waveform

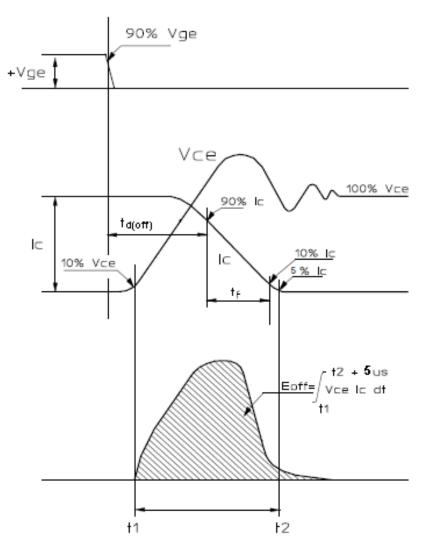
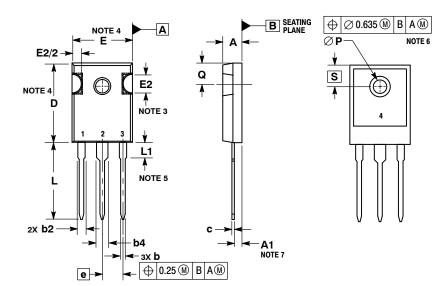


Figure 24. Definition of Turn Off Waveform

#### PACKAGE DIMENSIONS

#### TO-247 CASE 340AL **ISSUE A**



#### NOTES:

- 1 DIMENSIONING AND TOLERANCING PER ASME Y14 5M 1994
- CONTROLLING DIMENSION: MILLIMETERS.
- SLOT REQUIRED, NOTCH MAY BE ROUNDED.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST
- EXTREME OF THE PLASTIC BODY.
  LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- ØP SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE
- TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.
  DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

DY LI.			
	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.00	1.40	
b2	1.65	2.35	
b4	2.60	3.40	
0	0.40	0.80	
D	20.30	21.40	
E	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
Г	19.80	20.80	
L1	3.50	4.50	
P	3.55	3.65	
Q	5.40	6.20	
S	6.15 BSC		

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